

HAT2092R

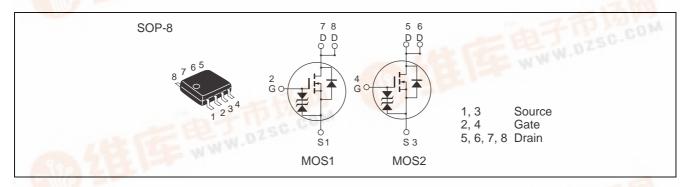
Silicon N Channel Power MOS FET High Speed Power Switching

REJ03G0511-0300 (Previous ADE-208-1236A(Z)) Rev.3.00 Jan.13.2005

Features

- Low on-resistance
- Capable of 4.5 V gate drive
- Low drive current
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	150 · I _D	11	А
Drain peak current	I _{D(pulse)} Note1	88	А
Body-drain diode reverse drain current	I _{DR}	11	А
Channel dissipation	Pch Note2	2	W
Channel dissipation	Pch Note3	3	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

- 2. 1 Drive operation: When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10s
- 3. 2 Drive operation: When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10s



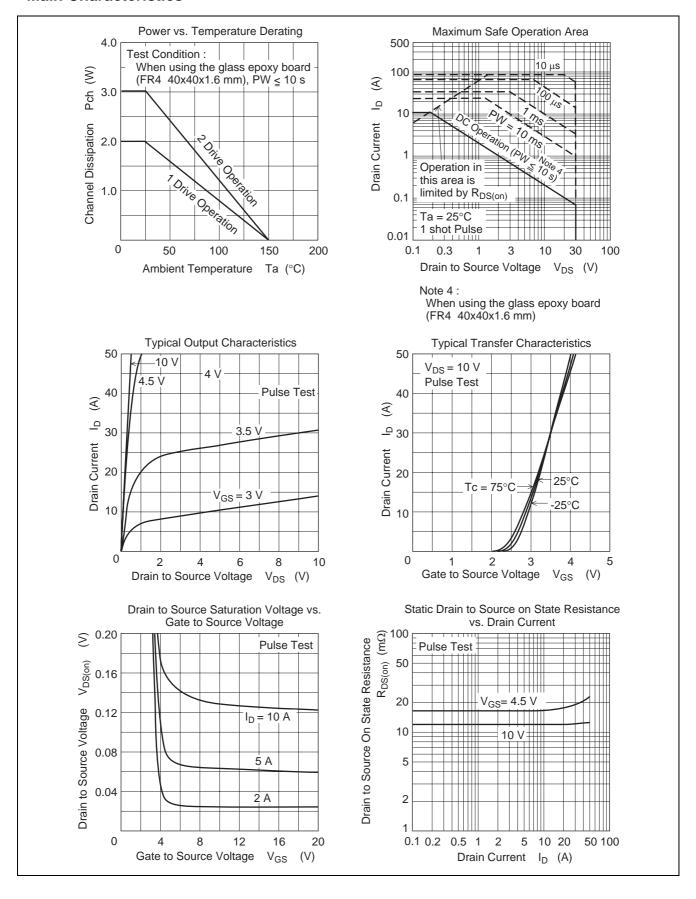
Electrical Characteristics

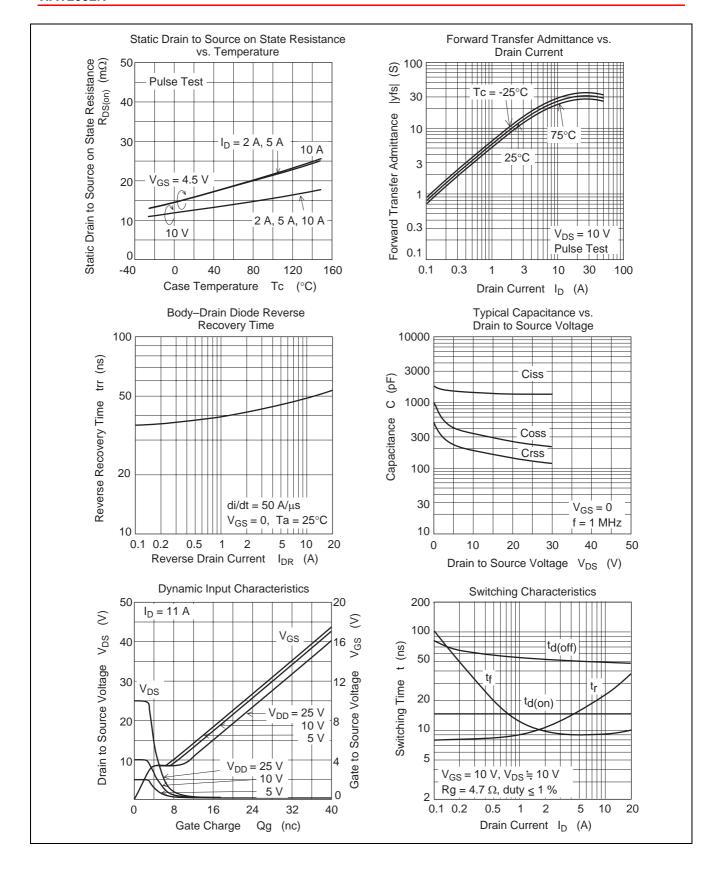
 $(Ta = 25^{\circ}C)$

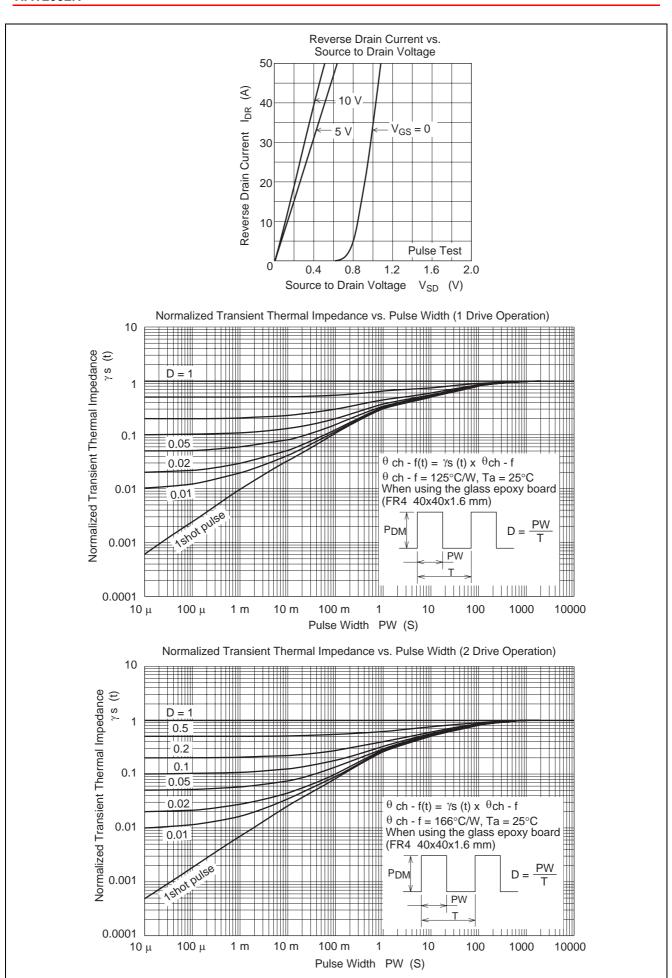
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I_{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state	R _{DS(on)}	_	13	16	mΩ	$I_D = 5.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$
resistance	R _{DS(on)}	_	17	25	mΩ	$I_D = 5.5 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note4}}$
Forward transfer admittance	y _{fs}	12	20	_	S	$I_D = 5.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	1400	_	pF	V _{DS} = 10V
Output capacitance	Coss	_	340	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	190	_	pF	f = 1MHz
Total gate charge	Qg	_	22	_	nc	V _{DD} = 10 V
Gate to source charge	Qgs	_	4	_	nc	V _{GS} = 10 V
Gate to drain charge	Qgd	_	4	_	nc	I _D = 11 A
Turn-on delay time	t _{d(on)}	_	15	_	ns	$V_{GS} = 10 \text{ A}, I_D = 5.5 \text{ A}$
Rise time	t _r	_	17	_	ns	V _{DD} ≅ 10 V
Turn-off delay time	t _{d(off)}	_	50	_	ns	$R_L = 1.83 \Omega$
Fall time	t _f	_	9	_	ns	$R_g = 4.7 \Omega$
Body-drain diode forward voltage	V_{DF}	_	0.85	1.10	V	IF = 11A, V _{GS} = 0 Note4
Body-drain diode reverse recovery time	t _{rr}	_	50	_	ns	IF = 11A, V _{GS} = 0 diF/ dt =50A/µs

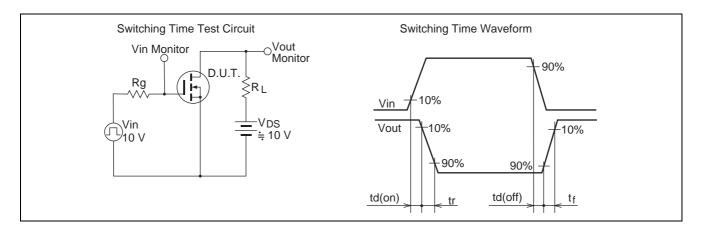
Note: 4. Pulse test

Main Characteristics

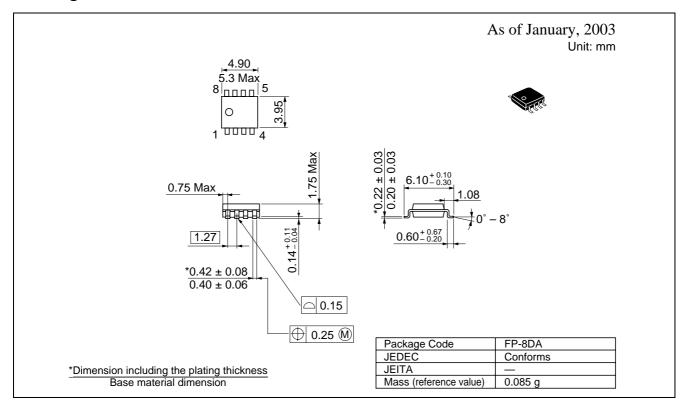








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2092R-EL-E	2500 pcs	Taping
HAT2092RJ-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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